

PHOTOCOUPLER

PS2815-1,PS2815-4

HIGH CTR, AC INPUT 4, 16-PIN SOP PHOTOCOUPLER

-NEPOC[™] Series-

DESCRIPTION

The PS2815-1 and PS2815-4 are optically coupled isolators containing GaAs light emitting diodes and an NPN silicon phototransistor in a plastic SOP for high density applications.

The package is an SOP (Small Outline Package) type for high density mounting applications.

FEATURES

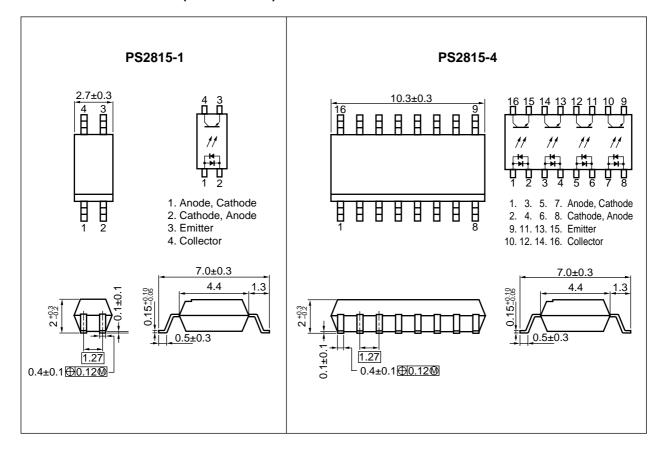
- · AC input response
- High current transfer ratio (CTR = 200 % TYP. @ $I_F = \pm 1$ mA)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Small and thin package (4, 16-pin SOP, Pin pitch 1.27 mm)
- Ordering number of taping product: PS2815-1-F3, F4, PS2815-4-F3, F4

APPLICATIONS

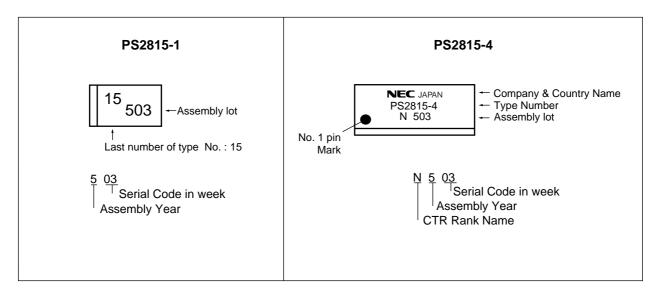
- · Programmable logic controllers
- Modem/FAX

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PACKAGE DIMENSIONS (in millimeters)



MARKING





ORDERING INFORMATION

Part Number	Package	Packing Style	Safety Standards Approval	Application Part Number*1
PS2815-1	4-pin SOP	50 pcs (Tape 50 pcs cut)	UL, BSI approved	PS2815-1
PS2815-1-F3		Embossed Tape 3 500 pcs/reel		
PS2815-1-F4				
PS2815-4	16-pin SOP	Magazine Case 45 pcs		PS2815-4
PS2815-4-F3		Embossed Tape 2 500 pcs/reel		
PS2815-4-F4				

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		
			PS2815-1	PS2815-4	Unit
Diode	Forward Current (DC)	I F	±50		mA
	Power Dissipation Derating	∆P _D /°C	0.6	0.7	mW/°C
	Power Dissipation	Po	60	70	mW/ch
	Peak Forward Current*1	I FP	±0.5		А
Transistor	Collector to Emitter Voltage	Vceo	40		V
	Emitter to Collector Voltage	VECO		5	V
	Collector Current	lc	4	.0	mA/ch
	Power Dissipation Derating	∆Pc/°C	1	.2	mW/°C
	Power Dissipation	Pc	12	20	mW/ch
Isolation Voltage ^{*2}		BV	2 500		Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100		°C
Storage Temperature		Tstg	−55 to +150		°C

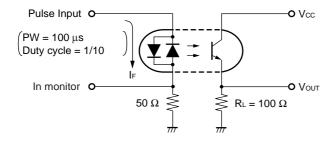
^{*1} PW = 100 μ s, Duty Cycle = 1 %

^{*2} AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

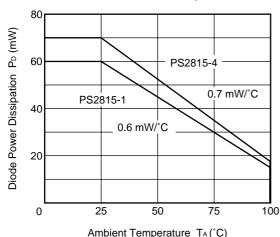
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I _F = ±5 mA		1.15	1.4	V
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		60		pF
Transistor	Collector to Emitter Current	Iceo	IF = 0 mA, VcE = 40 V			100	nA
Coupled	Current Transfer Ratio (Ic/IF)	CTR	IF = ± 1 mA, VcE = 5 V	100	200	400	%
	Collector Saturation Voltage	VCE (sat)	$I_F = \pm 1 \text{ mA}, I_C = 0.2 \text{ mA}$			0.3	V
	Isolation Resistance	Rı-o	Vi-o = 1 kVDC	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time*1	tr	$Vcc = 5 \text{ V}, \text{ Ic} = 2 \text{ mA}, \text{ RL} = 100 \Omega$		4		μs
	Fall Time*1	t f			5		

*1 Test circuit for switching time

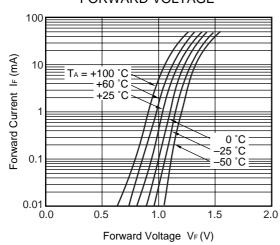


TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

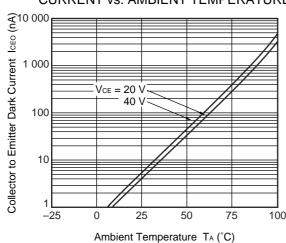




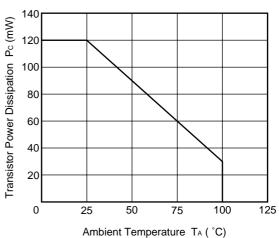
FORWARD CURRENT vs. FORWARD VOLTAGE



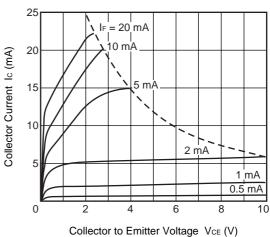
COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE



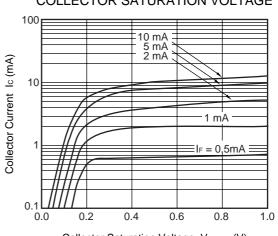
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

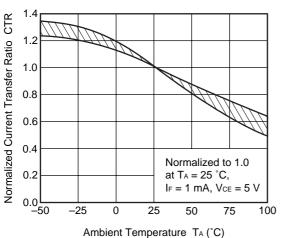


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

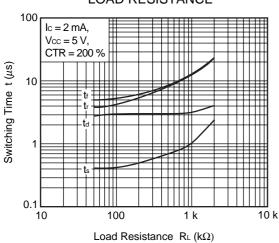


Collector Saturation Voltage VcE(sat) (V)

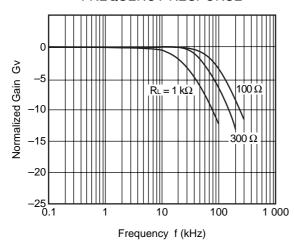
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

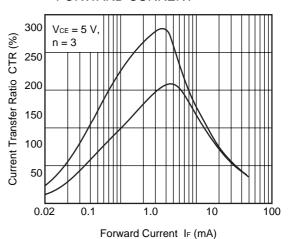


FREQUENCY RESPONSE

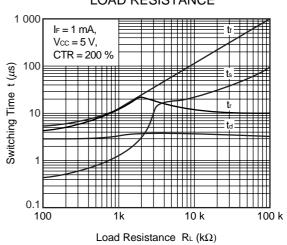


Remark The graphs indicate nominal characteristics.

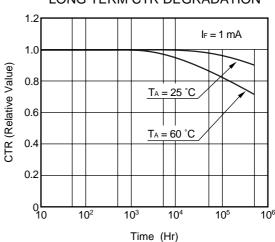
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



SWITCHING TIME vs. LOAD RESISTANCE

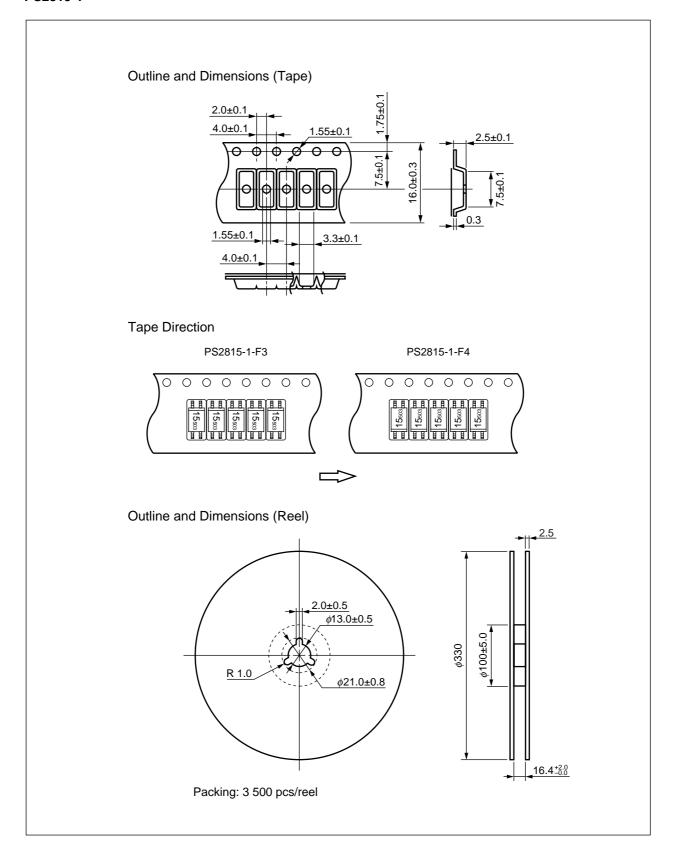


LONG TERM CTR DEGRADATION

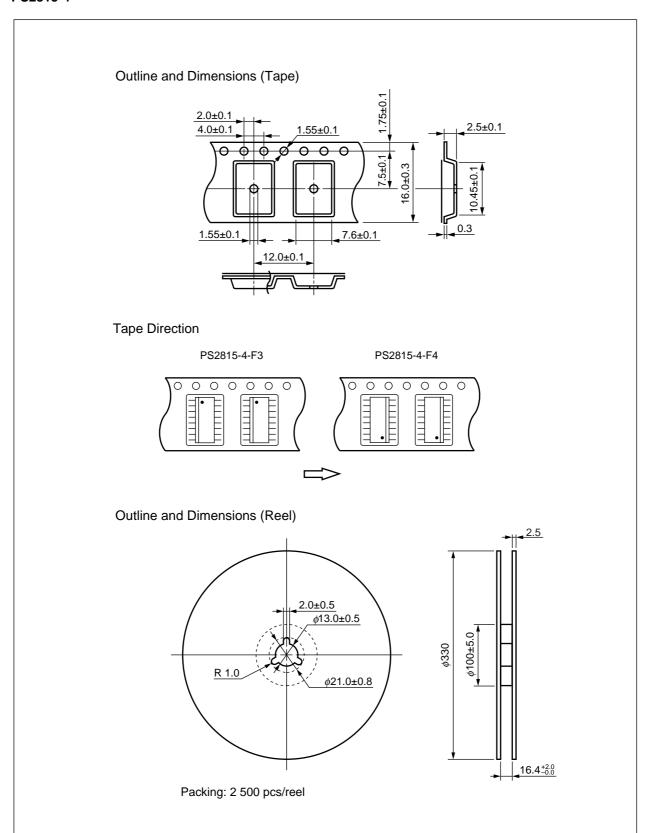


TAPING SPECIFICATIONS (in millimeters)

PS2815-1



PS2815-4



RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 235 °C or below (package surface temperature)

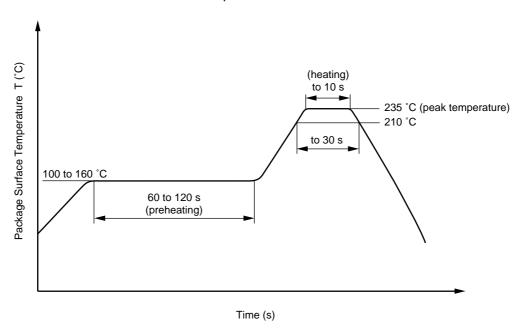
• Time of temperature higher than 210 °C 30 seconds or less

• Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Dip soldering

• Temperature 260 °C or below (molten solder temperature)

• Time 10 seconds or less

• Number of times One

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of

0.2 Wt % is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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M8E 00.4